

1. Solder ability and Solder Resistance

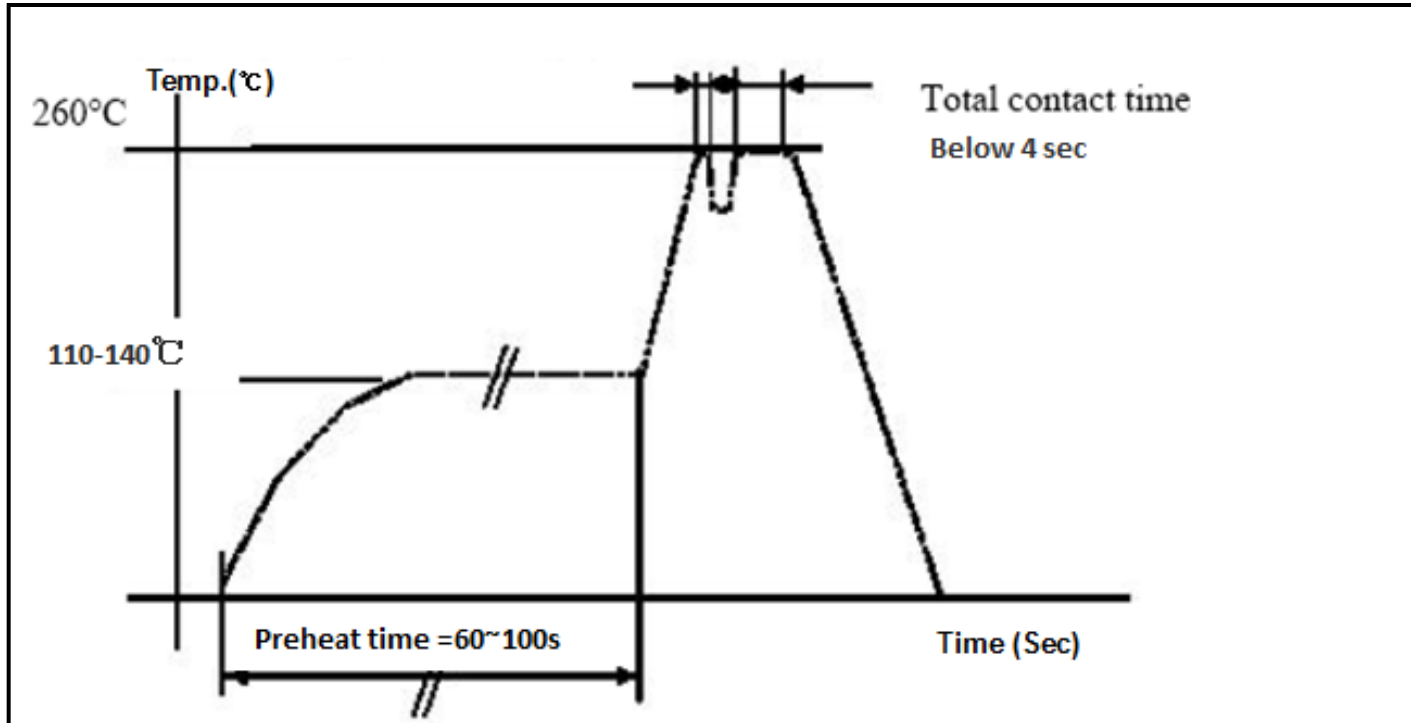
A. Solder ability

Lead solder able per JESD22-B102, method 1) (245°C / 5 seconds, 95% coverage of soldering area guaranteed)

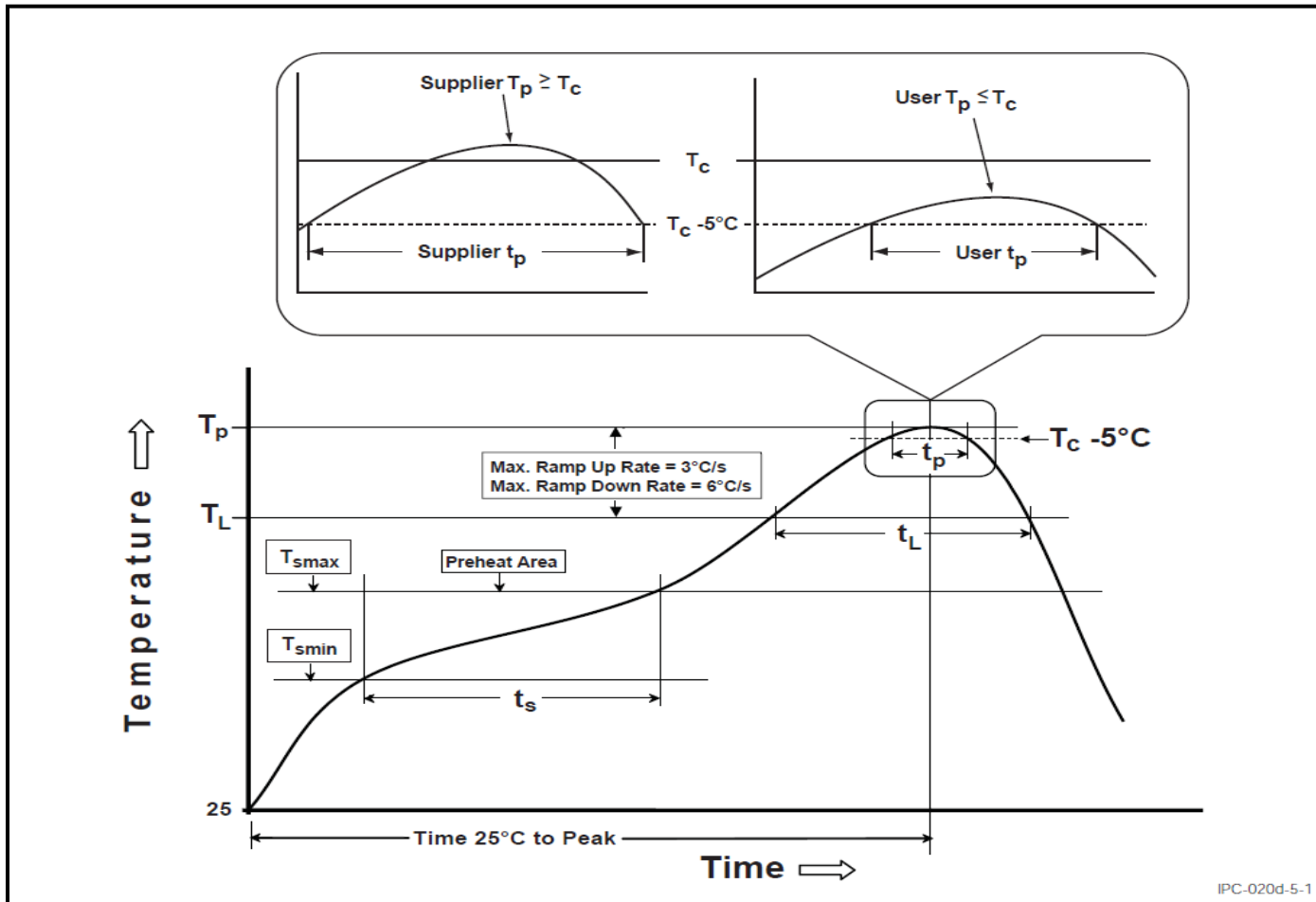
B. Solder Resistance

轴向/插件 : 270°C / 7 sec ; 贴片 : 260±5°C / 10 sec ;

a) Wave Soldering Profile



b) Reflow Soldering Profile (Pb free Application), refer to IPC/JEDEC J-STD-020



Recommended Soldering Profile for Rectifier Diodes (Pb Free)



YANGZHOU YANGJIE ELECTRONIC TECHNOLOGY CO.,LTD.

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|--|-----------------------------------|
| Preheat/Soak Temperature Min (T _{smin}) Temperature Max (T _{smax}) Time (ts) from (T _{smin} to T _{smax}) | 50 °C 200 °C 60-120 seconds |
| Melting Point of Solder (Sn Ag Cu) | 217°C |
| Ramp-up Rate to 217°C(Melting Point of Solder) | 3°C/sec |
| Time at Temp.>217°C (Melting Point of Solder) | 60~150 Sec |
| Peak Temperature | 255±5°C |
| Time within 5°Cbelow Peak Temp. | 20~40 Sec |
| Cooling Rate | 6°C/sec (max) |
| Time from 25°C to Peak Temp. | 8min (max) |